



US00D480638S

(12) **United States Design Patent**  
**Lee**

(10) **Patent No.:** **US D480,638 S**

(45) **Date of Patent:** **\*\* Oct. 14, 2003**

(54) **BLISTER PACK**

(75) Inventor: **Wai Chung David Lee, Kowloon (CN)**

(73) Assignee: **Koninklijke Philips Electronics N.V.,  
Eindhoven (NL)**

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/178,435**

(22) Filed: **Mar. 26, 2003**

(30) **Foreign Application Priority Data**

Oct. 16, 2002 (WO) ..... DMA/005 855

(51) **LOC (7) Cl.** ..... **09-03**

(52) **U.S. Cl.** ..... **D9/415**

(58) **Field of Search** ..... D9/414, 415, 418,  
D9/337, 457; 206/461-471, 806, 495, 769-776,  
761-765

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

5,429,241 A \* 7/1995 Althaus ..... 206/471  
D418,407 S \* 1/2000 Uzawa ..... D9/415

D431,461 S \* 10/2000 Glassman ..... D9/415  
D433,937 S \* 11/2000 Glassman ..... D9/415  
6,170,663 B1 \* 1/2001 Glassman ..... 206/462  
D438,103 S \* 2/2001 Edwards et al. .... D9/415  
D442,857 S \* 5/2001 Feeman ..... D9/415  
D458,839 S \* 6/2002 Weinstein et al. .... D9/415  
6,427,832 B1 \* 8/2002 Ali et al. .... 206/471  
D473,787 S \* 4/2003 Jones Jr. et al. .... D9/418

\* cited by examiner

*Primary Examiner*—Prabhakar Deshmukh

(74) *Attorney, Agent, or Firm*—Ernestine C. Bartlett

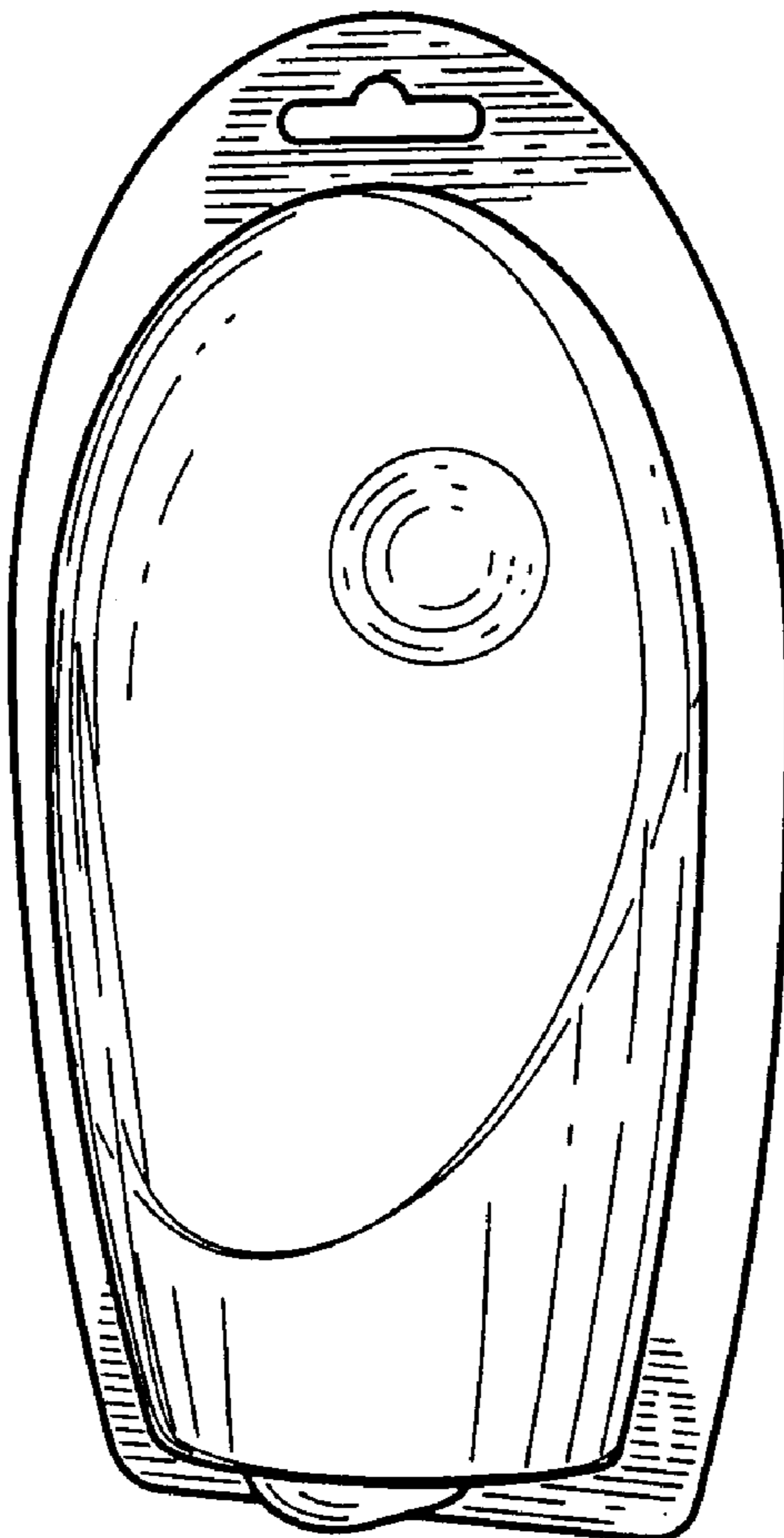
(57) **CLAIM**

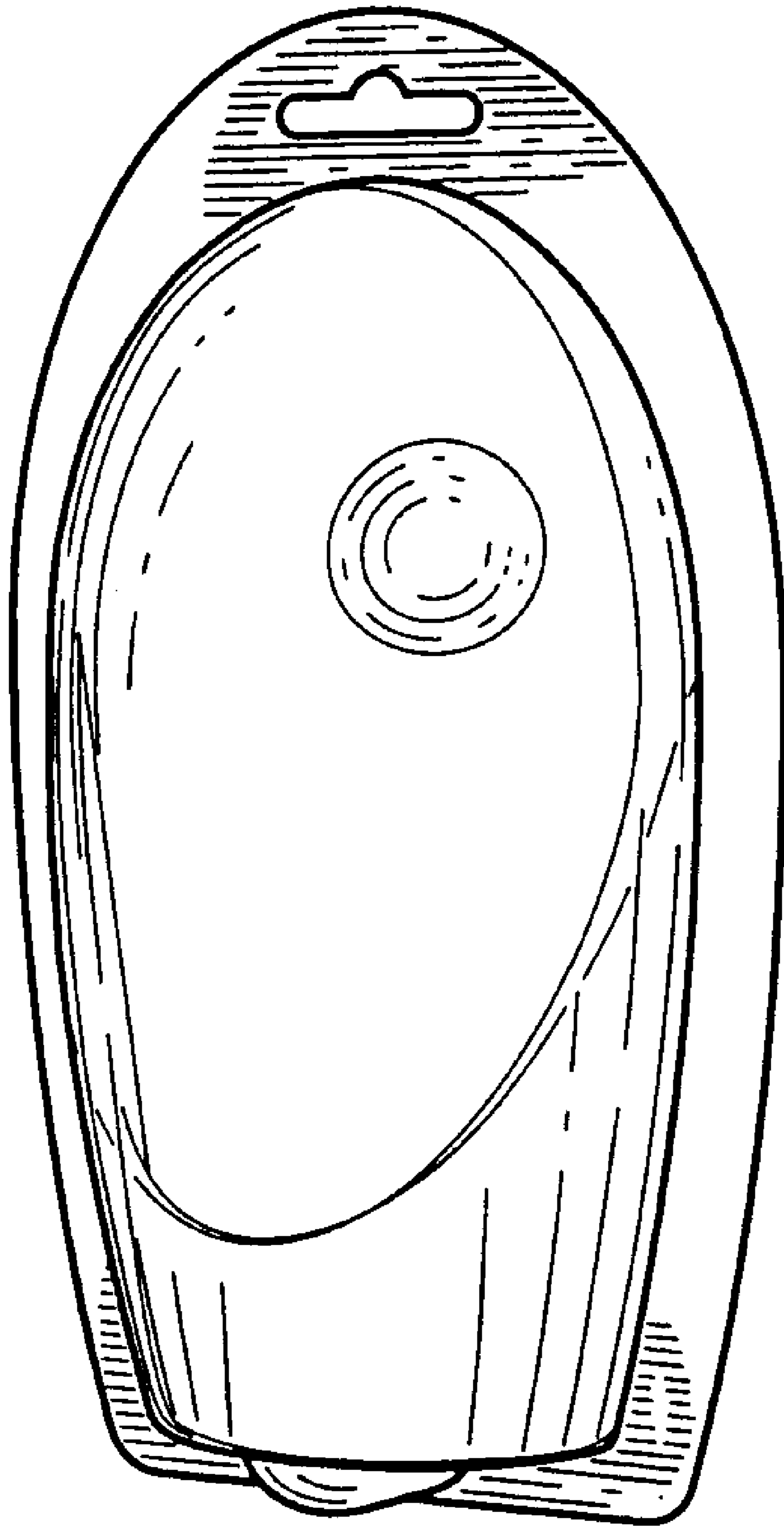
The ornamental design for a blister pack, as shown.

**DESCRIPTION**

FIG. 1 is a perspective view showing my design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a left side elevational view thereof;  
FIG. 5 is a right side elevational view thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.

**1 Claim, 3 Drawing Sheets**





**FIG. 1**

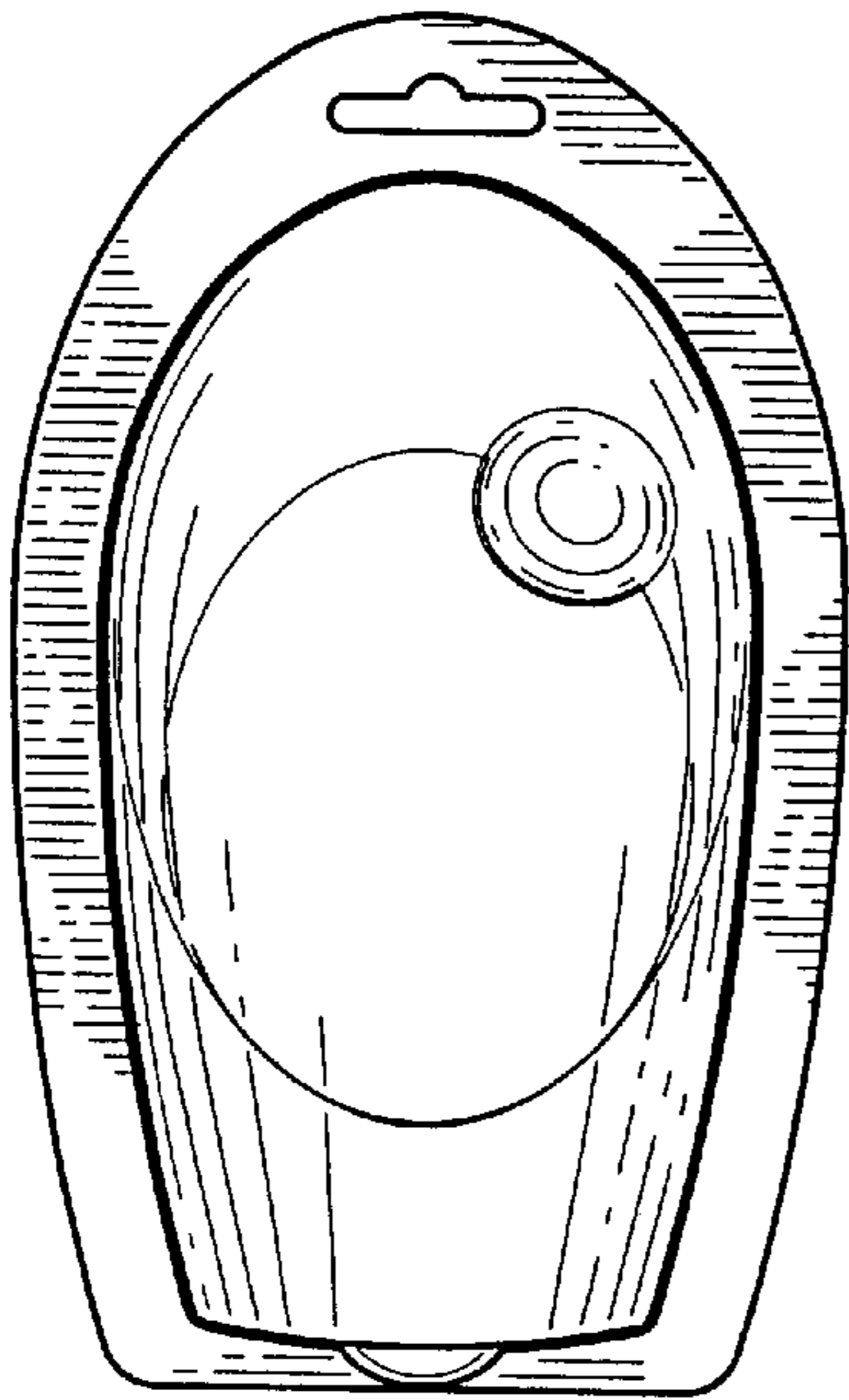


FIG. 2

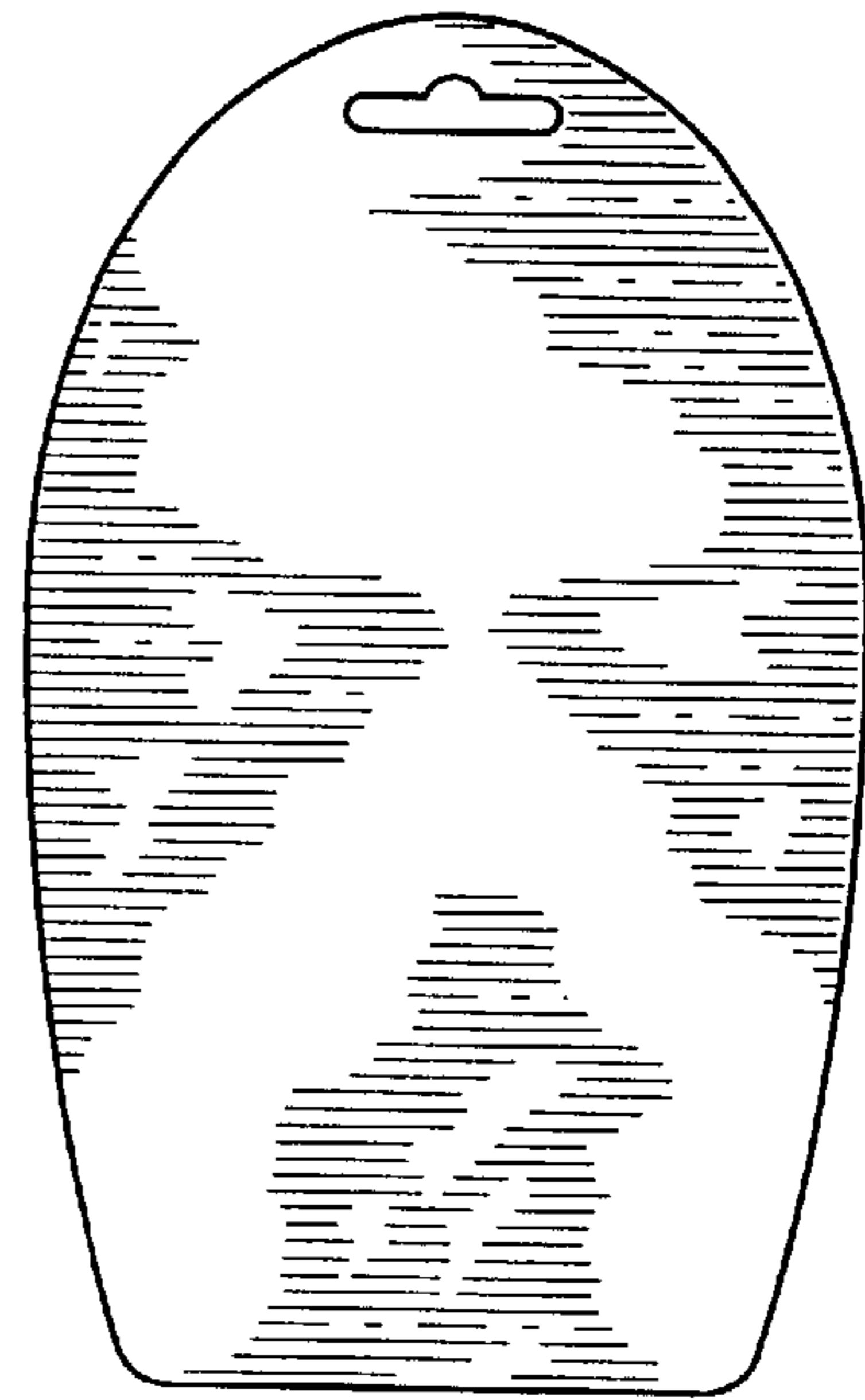


FIG. 3

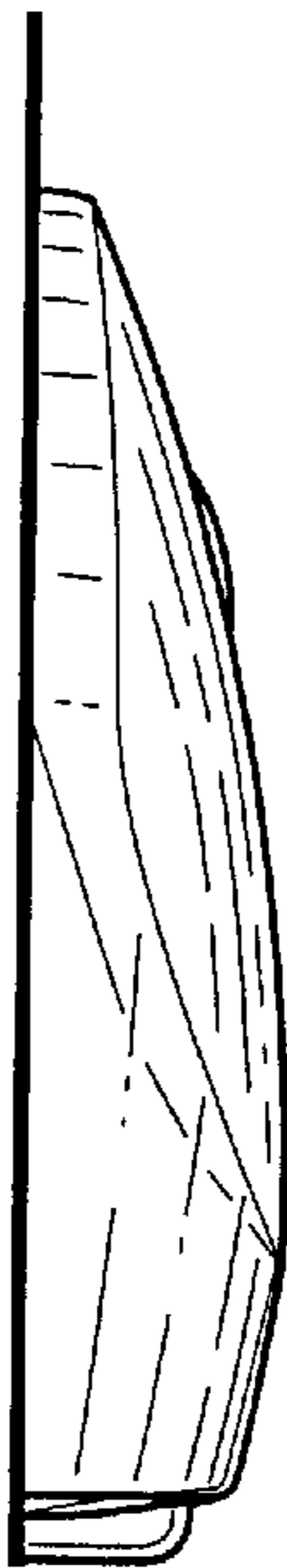


FIG. 4

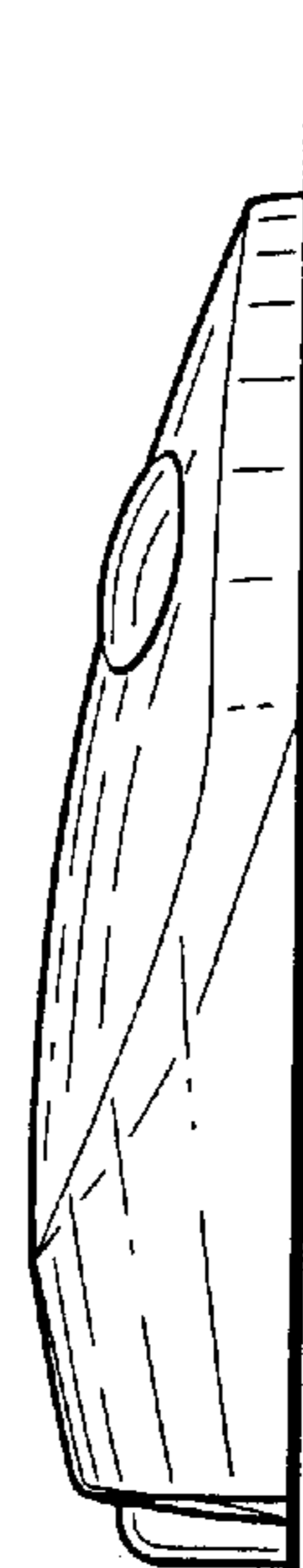


FIG. 5

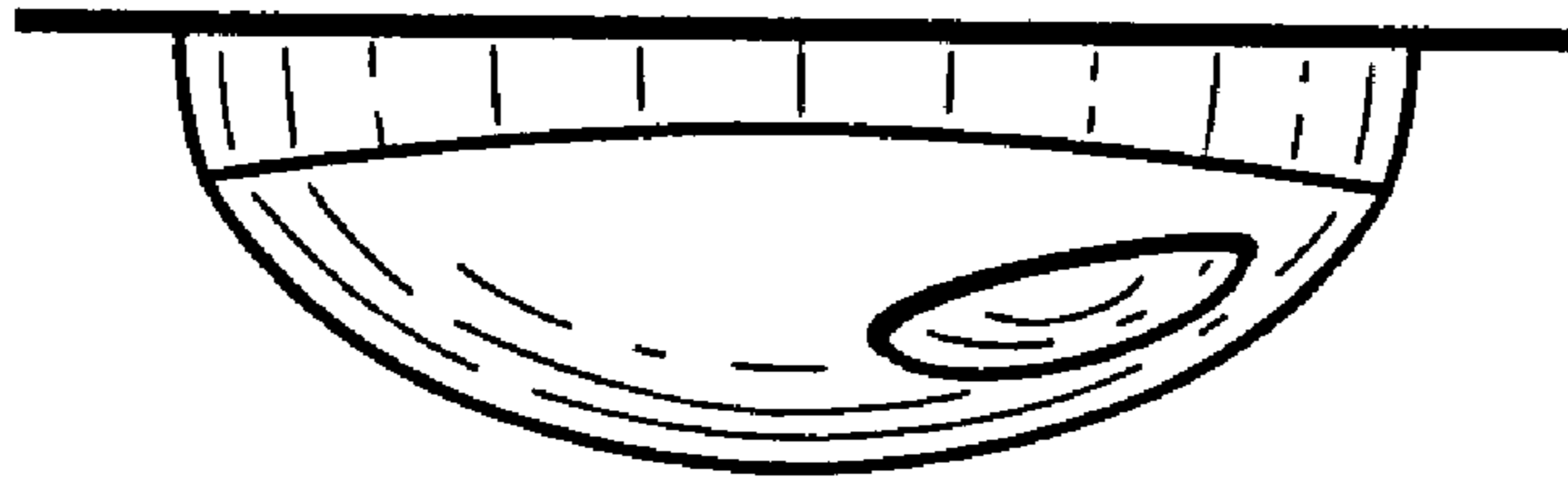


FIG. 6

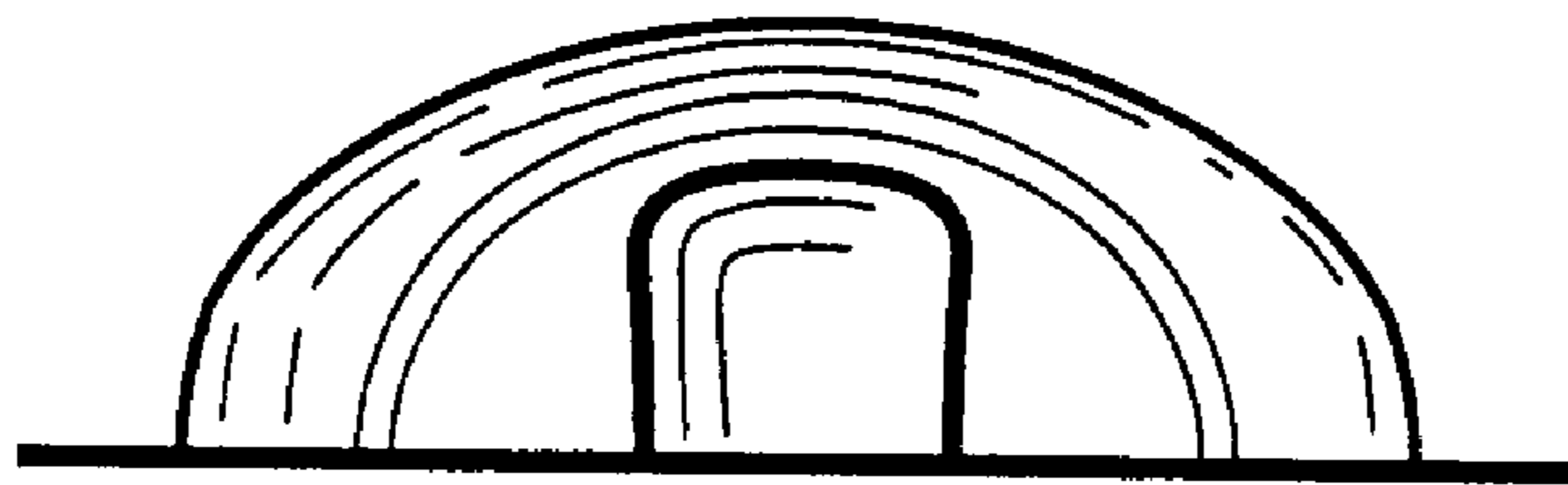


FIG. 7